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CONSTITUTION: Any type of polymer for constituting a layer of

SUBSTITUTION. Any type of polymer for constituting a layer of an organic polymer material can be used limited for use if it has a heat resistance of about 150°C. And, as a material in combination with the polymer material, a silicon oxide or silicon nitride is desirable, and a film is formed of it at 150°C or lower by a vacuum vapor-deposition method or a sputtering method. As a method for forming an organic polymer material layer, a vacuum vapor-deposition method, a sputtering method or a polymerizing method may be used. Polyimide and polyester of polymers to be used, are desirably formed as a film by the vacuum vapor-deposition method or the sputtering method.